

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	ECO 2136148: Initial Release	11/09/13	HPC
B	ECO 2138302: Up-dated title block, Removed references to Detector Amplifier Board Rev B, ESD and PCB document names	02/14/2014	HPC
C	ECO 2140557 : Update TEC Driver Top Drawing w/ mod	02/13/2014	GW
D	ECO 2140601: Update TEC Driver Top & Bottom Drawing	02/17/2014	GW

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		DWN/CHK Paul Cleveland	DATE 02/14/2014	CCA, NIRscan TEC Driver Board		
		SYS ENGR				
	0314CP	MANU				
NHA	USED ON	QA		SIZE <b>A</b>	DRAWING NO <b>2513473</b>	REV <b>D</b>
APPLICATION		APVD		SCALE NONE		SHEET 1 OF 5

**1. Scope**

The purpose of this document is to establish the assembly requirements for the TEC Driver Board.

**2. Related Documents**

Texas Instruments Documents

Dwg. Number	Document Name
2513471	2513471c_NIRscan_TEC_Driver_ESD
2513472	2513472c_NIRscan_TEC_Board_PCB

**3. Notes**

1. This PCB contains devices which are electrostatic discharge sensitive.
2. Mark the appropriate Manufacturing Serial Number (MSN) on the top of the PCB. Method and placement location optional.
3. Mark assembly number, assembly dash number and revision letter of CCA on the top of the PCB. Method and placement location optional.
4. Workmanship to be in accordance with ANSI/IPC-A-610B Class 2 and ANSI/J-STD-001A Class 2.
5. Equivalent or better part may be substituted.
6. Solder times and temperatures to be in conformance with PWB UL component recognition limits established for the particular board. The solder profile must also comply with the limits of all components on the PCB.
7. Components and processes should be lead-free and ROHS compliant.

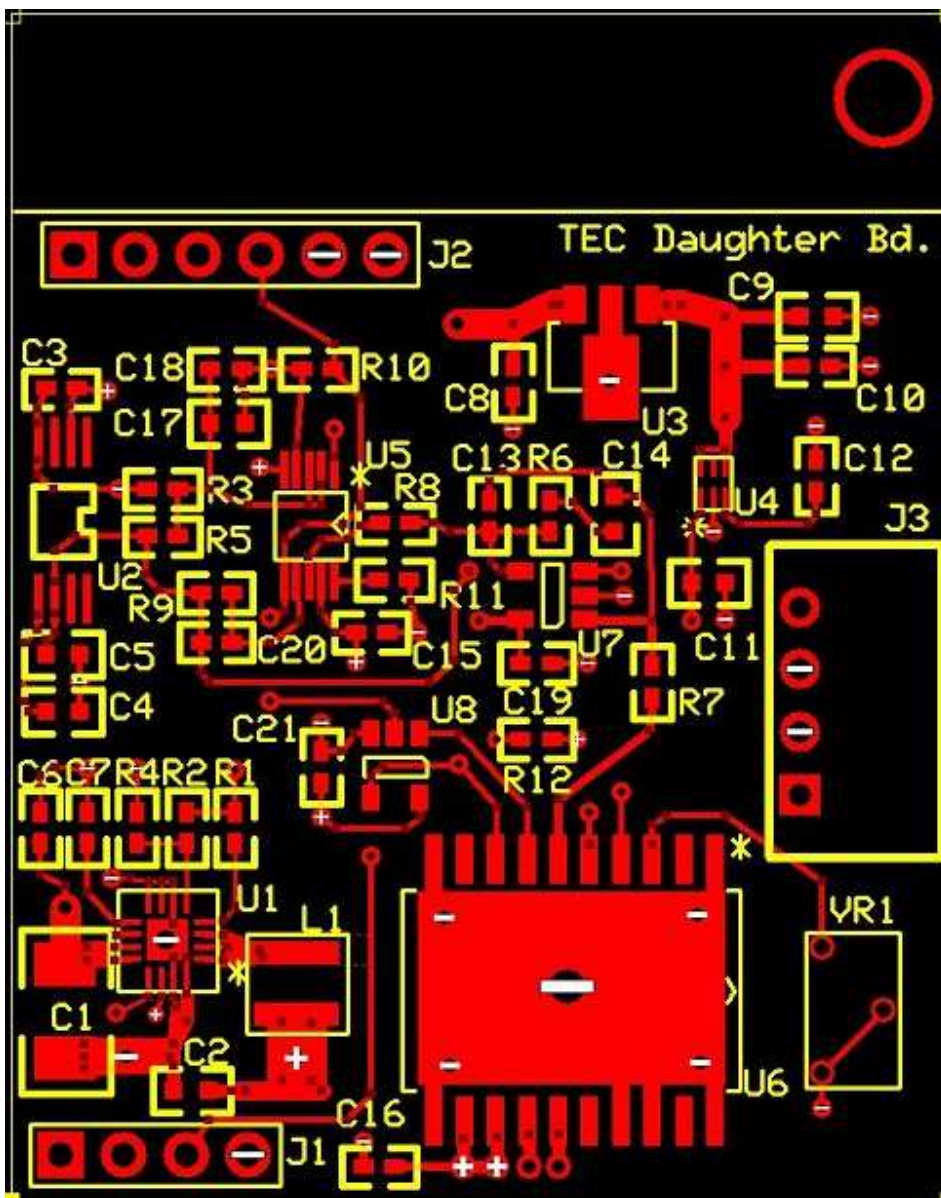
**4. Bill of Material & Cross Reference List**

Assembly bill of material and cross reference list are provided in attached spread sheet.

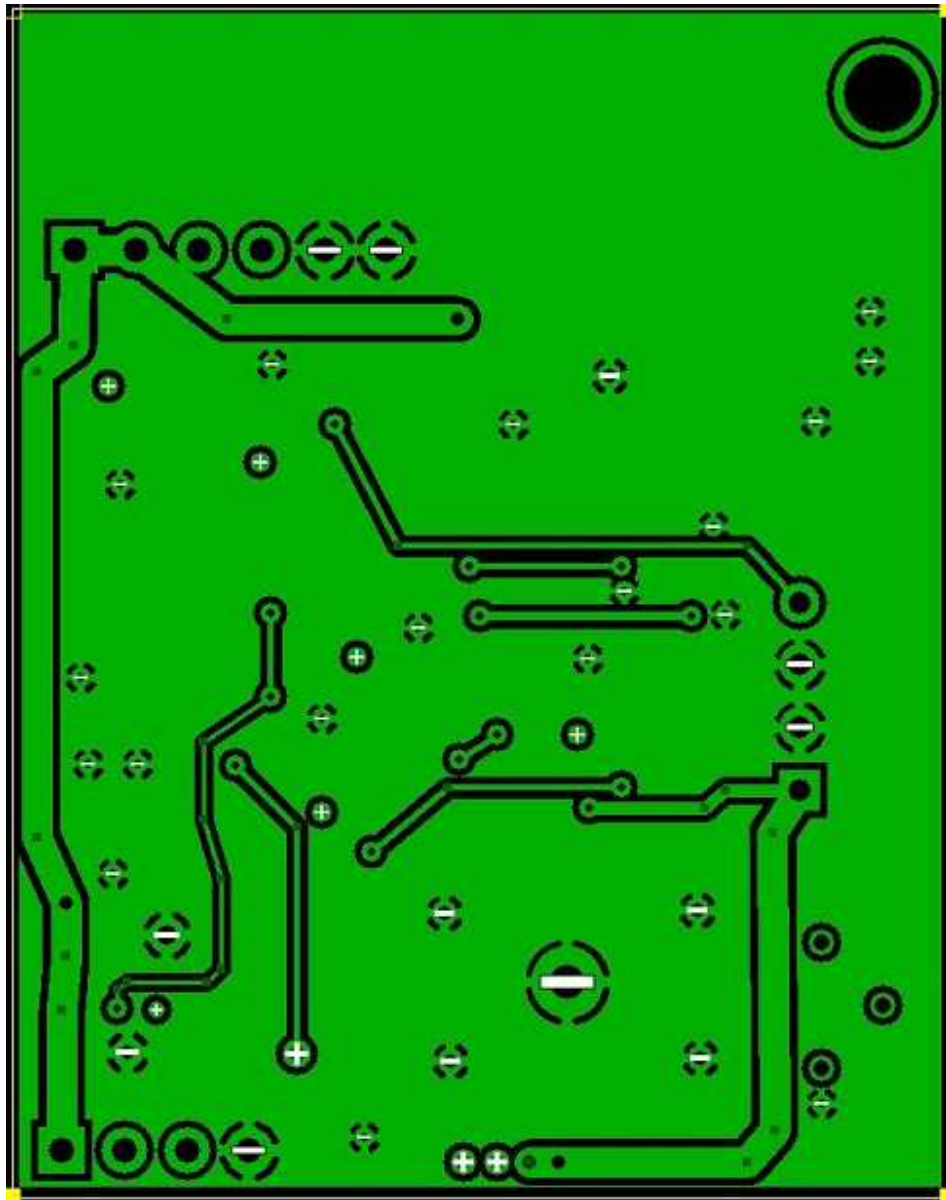
Assembly Dash	Description	Material & Cross Reference List Spread Sheet
-1	TEC Driver Board	2513474b_NIRscan_TEC_Driver_BOM.xls

## 5. Assembly Diagrams

### TEC Driver Top



TEC Driver Bottom



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